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16.03.2020

**OS-IN-2020-007**  
**Standardization of wirebond and introduction of new leadframe supplier for Micro SIDELED® 2808 (LW Y1SG)**

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<b>Objective</b>	Introduction of new Au-wire and leadframe supplier for Micro SIDELED® 2808 (LW Y1SG)
<b>Products affected</b>	LW Y1SG
<b>Background</b>	Increase of supply security. Harmonization of bond wire within Micro SIDELED family.
<b>Realization</b>	Please refer to the customer information package for detailed description of the change.
<b>Time Schedule</b>	Implementation date: 20 <sup>th</sup> of April 2020
<b>Assessment</b>	No change in fit, form, function and reliability of affected products.

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**Please direct your inquiry to your local Sales office.**

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**OS-IN-2020-007**

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**Customer information package**

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### 1. Reason for change

- Harmonization of bond wire within Micro SIDELED family.
- Increase of supply security.

### Assessment

- No change in fit, form and function of the product.

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## 2. Description of change

	Current status	New status
Leadframe supplier	Supplier A	Supplier B
Leadframe base material	Material A	Material A
Mold compound	Compound A	Compound A
Product dimensions	2.8 x 1.2 x 0.8	2.8 x 1.2 x 0.8
Au wire dimension	1.25 mil	1.0 mil

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### 3. Affected Products

Brand	Product name
Micro SIDELED® 2808	LW Y1SG

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### 4. Time schedule

500h qualification report: 1<sup>st</sup> of April 2020

Implementation date: 20<sup>th</sup> of April 2020

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**Thank you.**